

■ CONTEXT OF EU CHIPS ACT

Under the European Chips-Act, **EuroCDP** strengthens the European semiconductor ecosystem by removing technical and financial barriers to the design of cutting-edge chips. Its **Design Enablement Teams (DETs)** offer accelerated prototyping and pre-industrialization of chips through an integrated one-stop shop, enabling European fabless semiconductor companies to scale up faster and become globally competitive.

■ IC-DASH – KEY HIGHLIGHTS

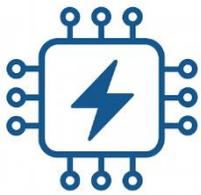
Based in France, the DET, IC-DASH operates as an **IC-design Acceleration Hub** supporting European fabless companies across the entire chip development journey – turning innovative ideas into market-ready silicon.

- ❖ **10 expert partners** covering the full supply chain
- ❖ **Embedded & edge chip design** made accessible
- ❖ Tailored for **startups, SMEs, and industrial players**
- ❖ Faster **time-to-market** with industrial-ready silicon solutions



■ WHY IC-DASH STANDS OUT ?

- **Secure cloud-based design environment**
 - ❖ Chip design platform ensuring protected and efficient development.
- **Industrial Emulation platform**
 - ❖ Early validation and fast iteration before tapeout.
- **End-to-end chip design services**
 - ❖ Expert support from specification to fabrication readiness.
- **Access to Cutting-Edge Technologies**
 - ❖ Power-efficient technologies, and more.
- **Integrated supply chain management**
 - ❖ Access to fabs, pilot lines, packaging and testing facilities, and supply chain management services.



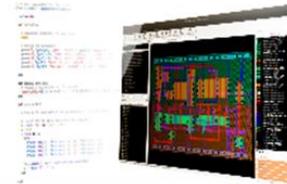
KEY FEATURES

Need analysis
Architecture review



CLOUD + EMULATION PLATFORM

- Setup and optimization of design flows
- Functional verification of ICs



DESIGN SERVICES

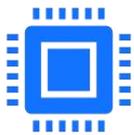
- Expert consulting services
- Spec. to GDSII



Full end-to-end support
across the entire chip design
value chain

FOUNDRY ACCESS

- MPWs, full reticle

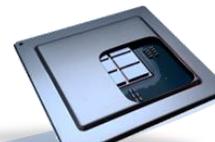


Custom solution
Supply chain management



ELECTRICAL TEST ON WAFER & PACKAGE & PRODUCTION

- Post silicon validation
- Test planning and execution up to volume production



PACKAGING AND ASSEMBLY

- Specifications and design

Quality Certifications: EN9100 (MilAero), Common Criteria (Security), ISO13485 (Medical), IATF16949 (Automotive), ESA, ISO9001

Product Certifications: DO160, DO178-C, DO254 Dal-x, ISO26262 ASIL-X, ISO 21434

APPLICATIONS

IC-DASH targets application-driven needs requiring **custom semiconductor components**, with a strong focus on **embedded and edge systems**. It supports sectors such as **aerospace, automotive, security, and medical**, where optimized, application-specific chips, **leveraging SOI technology expertise**, are essential. IC-DASH enables companies, **especially startups and growing SMEs**, to design **tailored, energy-efficient, and low-power solutions**, aligned with real industrial constraints and faster market deployment.

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